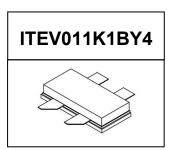
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1000W, 50V High Power RF LDMOS FETs

Description

The ITEV011K1BY4 is a 1000-watt capable, high performance, unmatched LDMOS FET, designed for HF/VHF. It can be used for both CW and pulse application.

It is featured for high power and high ruggedness, low cost, suitable for ISM RF Energy application.



• Typical Performance (On Innogration 108MHz fixture with device soldered):

ITEV011K1BY4 VGS=3.17V VDS=50V IDQ=450mA						
Signal	Signal Pout(dBm) Pout(W) Pin(dBm) Gain(dB) Eff(%) 2 nd /3 rd harmonic(dB)					
CW	60.3	1070	41.5	18.8	84	-21/-13

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- On chip RC network enable high stability and ruggedness
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Excellent thermal stability, low HCI drift
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	135	Vdc
GateSource Voltage	V _{GS}	-7 to +10	Vdc
Operating Voltage	V_{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case ,Case Temperature	Do 10	0.19	°C/W
80°C, 1000W CW, 50 Vdc, IDQ = 200 mA	R⊕JC	0.18	
Transient thermal impedance from junction to case	7th	0.045	0000
Tj = 150° C; tp = 100 us; Duty cycle = 10 %	Zth	0.045	°C/W

Table 3. ESD Protection Characteristics

Test Methodology	Class	
Human Body Model (per JESD22A114)	Class 2	

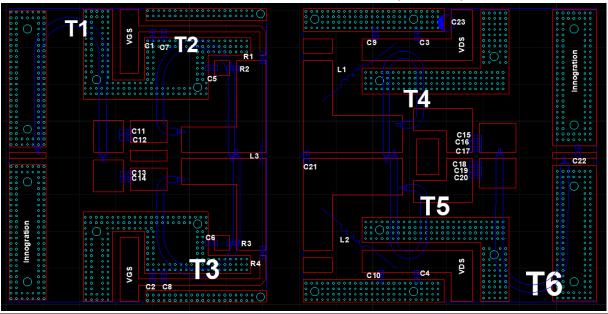
Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics (Per Side)					
Drain-Source Voltage	\/		135		\/
V _{GS} =0, I _{DS} =18.0mA	$V_{(BR)DSS}$		135		V

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		=	Tellitilitary Dat	
Zero Gate Voltage Drain Leakage Current	I _{DSS}		1	μА
$(V_{DS} = 50V, V_{GS} = 0 V)$				
Gate—Source Leakage Current	I _{GSS}		1	μА
(V _{GS} = 10 V, V _{DS} = 0 V)	IGSS		ı	μА
Gate Threshold Voltage	V _{GS} (th)	2.6		V
$(V_{DS} = 50V, I_D = 600 \mu A)$	V GS(III)	2.0		V
Gate Quiescent Voltage	V	3.17		V
$(V_{DD}$ = 50 V, I_{D} =450 mA, Measured in Functional Test)	$V_{GS(Q)}$	5.17		V
Common Source Input Capacitance	C _{ISS}	375		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Each section side of device				
measured				
Common Source Output Capacitance	Coss	108		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Each section side of device				
measured				
Common Source Feedback Capacitance	C _{RSS}	2.4		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Each section side of device				
measured				

Reference Circuit of Test Fixture (108MHz)



Component	Description	Suggestion
C1~C6	10uF/200V-1210	Ceramic multilayer capacitor
C7~10	10nF/200V-1210	Ceramic multilayer capacitor
C11~C14	150pF	
C15~C20	560pF	
C21	24pF	
C22	12pF	mica capacitor
C23	4700uF/63V	electrolytic capacitor

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T1	50 ohm-150mm	RFSFBU-086-50	
T2,T3	25 ohm-150mm	RFSFBU-086-25	
T4,T5	12.5 ohm-130mm	SFF-12.5-3	
T6	50 ohm-150mm		SFF-50-3
R1,R4	300 ^Ω -1206	Chip Resistor	
R2,R3	51 Ω -2512		Chip Resistor
L1,L2	1.5mm wire ,5mm inner diameter, 5	Turns	DIY
L3	1.5mm wire ,5mm inner diameter, 3	DIY	

Typical performance

Figure 1: Power Gain, Efficiency as function of Pout

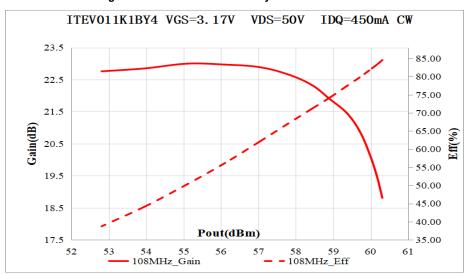
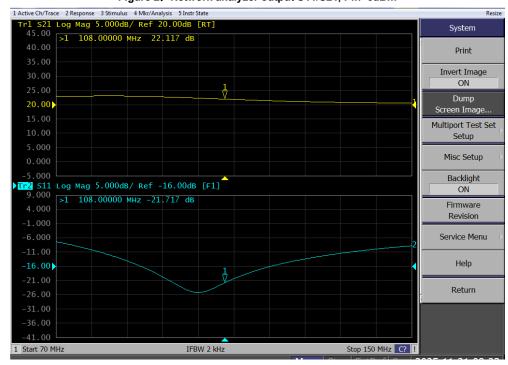
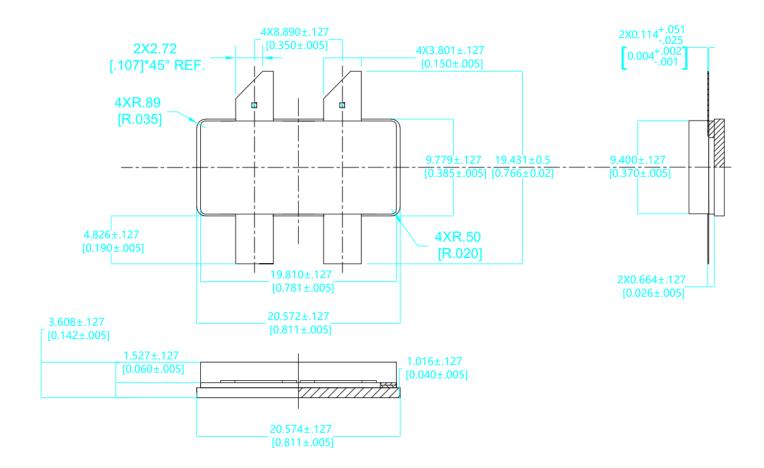


Figure 2: Network analyzer output S11/S21, Pin=0dBm



Earless Flanged Ceramic Package; 4 leads



OUTLINE REFERENCE			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	1000E DATE
PKG-BY4					07/27/2023

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Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2025/11/24	Rev 1.0	Preliminary Datasheet

Application data based on TC-25-40

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